

Title (en)

METHOD FOR MANUFACTURING AN ELEMENT HAVING ELECTRICALLY CONDUCTIVE MEMBERS FOR APPLICATION IN A MICROELECTRONIC PACKAGE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ELEMENTS MIT ELEKTRISCH LEITFÄHIGEN TEILEN ZUR ANWENDUNG FÜR EIN MIKROELEKTRONISCHES GEHÄUSE

Title (fr)

PROCEDE DE FABRICATION D'UN ELEMENT COMPORTANT DES ELEMENTS ELECTRIQUEMENT CONDUCTEURS POUR UNE APPLICATION DANS UN BOITIER MICROELECTRONIQUE

Publication

EP 2140489 A1 20100106 (EN)

Application

EP 08737816 A 20080411

Priority

- IB 2008051391 W 20080411
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Abstract (en)

[origin: WO2008126043A1] A microelectronic package (31) has a microelectronic device, which is encapsulated in a quantity of material (27), and a lead frame element (15) for enabling the microelectronic device to be electrically contacted from outside of the package (31). The lead frame element (15) comprises at least two elongated members (11) comprising electrically conductive material and a filling material (12) comprising electrically insulating material, wherein the members (11) are partially embedded in the filling material (12). The lead frame element (15) is manufactured by providing elongated members (11), positioning the members (11) according to a predetermined configuration, providing filling material (12) to spaces (13) which are present between the members (11), and possibly removing portions of the filling material (12) and the members (11) in order to expose the electrically conductive material of the members (11). An important advantage of manufacturing the lead frame element (15) on the basis of elongated members (11) and a filling material (12) is that no waste or only a small quantity of waste is produced.

IPC 8 full level

H01L 23/498 (2006.01); **H01L 23/473** (2006.01); **H01L 23/48** (2006.01)

CPC (source: EP US)

H01L 21/4846 (2013.01 - EP US); **H01L 23/4985** (2013.01 - EP US); **H01L 23/49861** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05554** (2013.01 - EP US); **H01L 2224/451** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/10161** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H01L 2924/1461** (2013.01 - EP US); **H01L 2924/15747** (2013.01 - EP US); **Y10T 29/49194** (2015.01 - EP US)

C-Set (source: EP US)

1. **H01L 2924/01015** + **H01L 2924/00**
2. **H01L 2924/1461** + **H01L 2924/00**
3. **H01L 2924/15747** + **H01L 2924/00**
4. **H01L 2224/451** + **H01L 2924/00014**
5. **H01L 2924/12041** + **H01L 2924/00**

Citation (search report)

See references of WO 2008126043A1

Designated contracting state (EPC)

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